



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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TSF-6522

No-Clean Tacky Soldering Flux

Product Description

Kester TSF-6522 is a no-clean tacky soldering flux formula designed to be used with a rotating disc, a doctor blade, or a drum fluxer. Kester TSF-6522 can also be used in dot dispensing for BGA/PGA sites or in a rework application for surface mount packages. Kester TSF-6522 maintains its activity and dispensing characteristics for up to 8 hours and can be used in a wide range of temperature and humidity conditions. Kester maintains the highest standards by manufacturing TSF-6522 under a vacuum environment.

Performance Characteristics:

- High tack values and long tack life
- Leaves bright/shiny solder joints after reflow
- Can reflow in air or nitrogen environments
- Classified as ROL0 per J-STD-004
- Compliant to Bellcore GR-78

Physical Properties

Viscosity (typical): 285 poise

Malcom Viscometer @ 10rpm and 25°C

Initial Tackiness (typical): 100 grams

Tested to J-STD-005, IPC-TM-650, Method 2.4.44

Acid Number: 75.4 mg KOH/g of flux

Tested to J-STD-004, IPC-TM-650, Method 2.3.13

Reliability Properties

Copper Mirror Corrosion: Low

Tested to J-STD-004, IPC-TM-650, Method 2.3.32

Corrosion Test: Low

Tested to J-STD-004, IPC-TM-650, Method 2.6.15

Silver Chromate: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.33

Chloride and Bromides: None Detected

Tested to J-STD-004, IPC-TM-650, Method 2.3.35

Fluorides by Spot Test: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

SIR, IPC (typical): Pass

Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3

	Blank	TSF-6522
Day 1	$3.1 \times 10^{10} \Omega$	$2.6 \times 10^8 \Omega$
Day 4	$1.3 \times 10^{10} \Omega$	$4.2 \times 10^8 \Omega$
Day 7	$8.8 \times 10^9 \Omega$	$6.4 \times 10^8 \Omega$

Application Notes

Standard Applications:

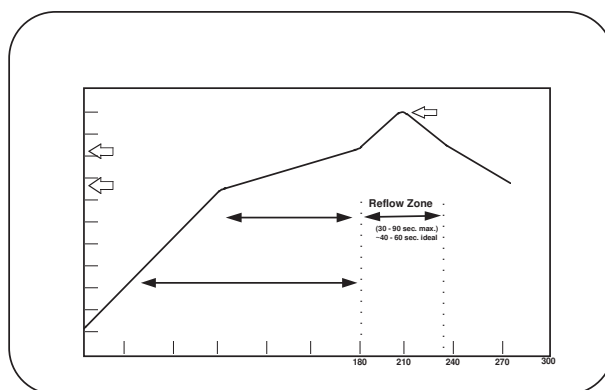
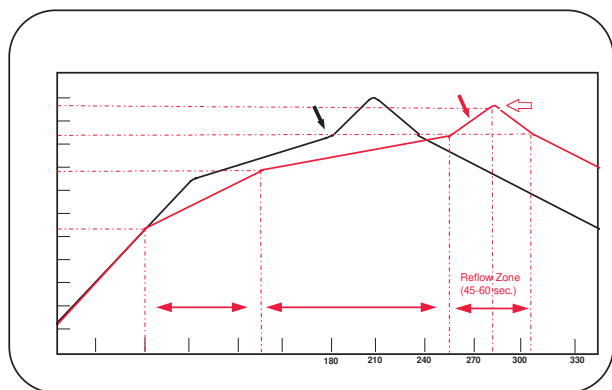
TSF-6522 was designed for pin transfer, dot dispensing and/or syringe applications. This flux can be used as a tack and flux vehicle for soldering components to a solid solder deposit (SSD), or precision pad technology (PPT) board surfaces. TSF-6522 is great for rework applications on all PCB packages. TSF-6522 can be used in BGA/PGA sphere/pin attachment vehicle or for repair and reballing/repinning. This flux works on flip chip, chip scale package and flip chip bumping sites assemblies as a soldering flux.

Printing Parameters:

Temperature/Humidity Optimal ranges are 21-25°C (70-77°F) and 35-65% RH

Recommended Reflow Profiles:

Optimal activation temperatures are 130°-185°C (266-365°F). See "Soak Zone" in diagrams below.



Cleaning:

TSF-6522 is a no-clean chemistry. The residues do not need to be removed for typical applications. If residue removal is required, call Kester Technical Support.

Storage, Handling, and Shelf Life:

Refrigeration is the recommended optimum storage condition for TSF-6522 to maintain consistent viscosity, reflow characteristics and overall performance. TSF-6522 should be stabilized at room temperature prior to printing. TSF-6522 should be kept at standard refrigeration conditions, 0-10°C (32-50°F). Please contact Kester if you require additional advice with regard storage and handling of this material. Shelf life is 3 months from date of manufacture when handled properly and held at 0-10°C (32-50°F).

Health & Safety:

This product, during handling or use, may be hazardous to health or the environment. Read the Material Safety Data Sheet and warning label before using this product.

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